

Tervetuloa O-johtavaan

O-Leading pyrkii olemaan yhden luokun ratkaisukumppani EMS-toimitusketjussa, mukaan lukien piirilevyjen suunnittelu, piirilevyjen valmistus ja piirilevyjen kokoaminen (PCBA). Tarjoamme joitain edistyneimmistä piirilevyteknikoista, mukaan lukien HDI-piirilevyt, monikerroksiset piirilevyt, jäykät ja joustavat piirilevyt. Voimme tukea prototyypin nopeasta kääntämisestä keskisuurten ja massatuotantoon. ([Kaksipuolinen pcb-valmistaja Kiina](#))

Yleisesti ottaen globaalit asiakkaamme ovat erittäin vaikuttuneita palveluistamme: nopea reagointi, kilpailukykyinen hinta ja sitoutuminen laatuun. Arvokkaamman teknisen palvelun ja kokonaisratkaisun tarjoaminen on O-tapa edetä.

Tulevaisuuden näkökulmasta O-johtava keskittyy aina elektroniikan valmistustekniikan innovaatioihin ja kehitykseen ja pyrkii jatkuvasti PCB:n ja PCBA:n keskitettyyn palveluun tarjoamaan ensiluokkaisia palveluita ja luomaan enemmän arvoa asiakkaillemme.

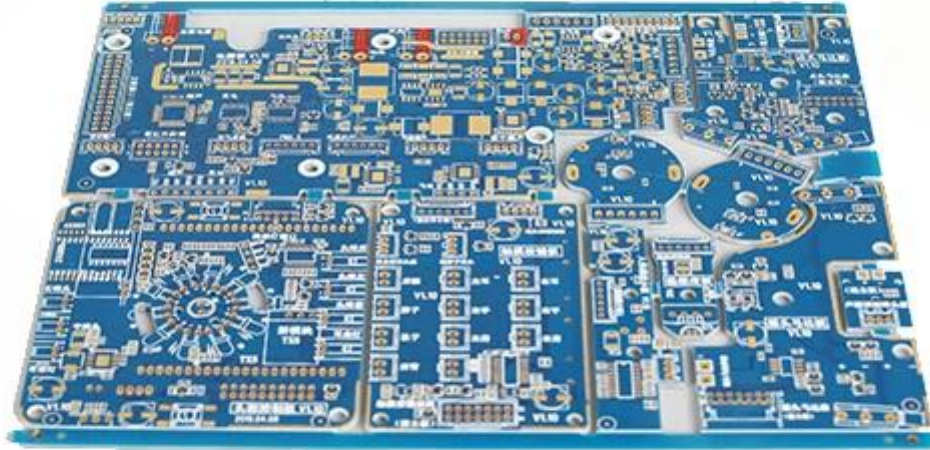
Olemme ammattimainen piirilevyjen valmistaja, jolla on yli kymmenen vuoden kokemus. Tuotevalikoima: yksi, kaksipuolinen, monikerroksinen piirilevy, joustava piirilevy ja MCPCB. Voimme tarjota nopean prototyypipalvelun - S / S 24 tuntia, 4-8 kerrosta 48-96 työtuntia.

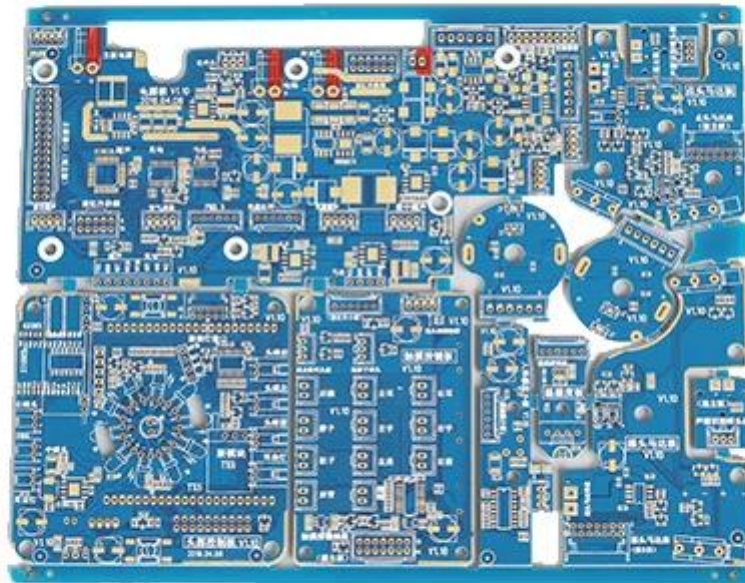
KUPARINMATTALENKOEN reikiä MINIMM .025 AVG, .020 MIN .. reikiä EI voi kytkeä, [Kaksipuolinen pcb Kiinassa](#)

Pakkaus värittömällä läpinäkyvällä kuplakalvolla, 25 kpl / pussi, laita kuivausaine kylkeen, laita kosteuden ilmaisinkortti yläpuolelle

Tuotteen Kuvaus

PCB P / N	Virtalähteen pääpiirilevy sinisellä juotosmaskilla
Kerros Count	2L
Material	FR-4 TG130
Hallitus thk	1.60mm
kupari thk	1 / 1oz
Pienin reikä size	0.30mm
Reikien lukumäärä (kpl)	879
linja w / s	8 / 7mil
Impedanssisäätö. KYLLÄ / EI (Tol%)	N
Pinnan viimeistely	ENIG Au: 0,05-0,10UM
Juotosmaskin silkkipaino	Sinivalkoinen
Yhden hallituksen koko	Himmennetty X (mm): 139; Himmeä Y (mm): 75
Panelisation	Himmeä X (mm): 139; himmeä Y (mm): 85; UPS: n määrä: 1
Special: irrotettava naamio	N
Reititys / Lävistys	CNC





www.o-leading.com

- [Kaksipuolinen pcb-toimittaja](#)

Tiimimme



Factory PCB



Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

Factory SMT







Test Report

No. SZXEC1900530401 Date: 30 Mar 2019 Page 1 of 6

O-LEADING SUPPLY CHAIN (HK) CO., LIMITED
1313.FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG, CHINA

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. : RP19-006089 - SZ
Date of Sample Received : 22 Mar 2019
Testing Period : 22 Mar 2019 - 30 Mar 2019
Test Requested : Selected test(s) as requested by client.
Test Method : Please refer to next page(s).
Test Results : Please refer to next page(s).

Conclusion : Based on the performed tests on submitted sample(s), the results of Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBDEs) and Phthalates such as Bis(2-ethylhexyl) phthalate (DEHP) , Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP) , and Diisobutyl phthalate (DIBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.

Signed for and on behalf of
SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

Tina

Tina Fan
Approved Signatory



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Test Report

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Test Results :

Test Part Description :

Specimen No. : SN1
SGS Sample ID : SZX19-005304.001
Description : Green"PCB"

Remarks :

- (1) 1 mg/kg = 1 ppm = 0.0001%
(2) MDL = Method Detection Limit
(3) ND = Not Detected (< MDL)
(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC 62321-5:2013, IEC 62321-7-2:2017, IEC 62321-6:2015 and IEC 62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Table with 5 columns: Test Item(s), Limit, Unit, MDL, and 027. Rows include Cadmium (Cd), Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr(VI)), Sum of PBBs, Monobromobiphenyl, Dibromobiphenyl, Tribromobiphenyl, Tetrabromobiphenyl, Pentabromobiphenyl, Hexabromobiphenyl, Heptabromobiphenyl, Octabromobiphenyl, Nonabromobiphenyl, Decabromobiphenyl, Sum of PBDEs, Monobromodiphenyl ether, Dibromodiphenyl ether, Tribromodiphenyl ether, Tetrabromodiphenyl ether, and Pentabromodiphenyl ether.



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ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

Wiring, Printed - Component

See General Information for Wiring, Printed - Component

O-LEADING SUPPLY CHAIN (HK) CO LTD
 ROOM 1205, 12/F
 TAI SANG BANK BLDG
 130-132 DES VOEUS ROAD
 CENTRAL, HONG KONG

E490354

Type	Cond Width		Cond Thk	SS/ DS/ DSO	Max	Max		Meets	C			
	Min	Edge			Area	Solder Limits	Oper Temp			Flame		
	mm(in)	mm(in)	mic(mil)		mm(in)	C	sec	C	Class	UL796	DSR	I
Multilayer (mass laminate) printed wiring boards.												
O-LEADING-401	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-	-	
O-LEADING-407	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-	
Multilayer printed wiring boards.												
O-LEADING-408	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All	*	
Single layer printed wiring boards.												
O-LEADING-002	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-	
O-LEADING-003	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	▲	-	
O-LEADING-033	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	-	
O-LEADING-205	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	-	
O-LEADING-206	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	-	
O-LEADING-D01	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All	*	
O-LEADING-S01	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All	*	

WIRING, PRINTED - COMPONENT | UL Product iQ

O-LEADING-S02	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	HB	▲	*	
O-LEADING-S03	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All	*	

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

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Shipping service



Quick Turn Lead Time		
Layer Count:	Lead Tim	Special Requirement
1L/2L	2-3days	24 Hours,48 Hours
4L	3-4days	48 Hours
6L	4-5days	72 Hours
8L	5-6days	NA
10L	6-7days	NA
12L	7-8days	NA
14L	8-9days	NA

Standard Lead Time		
Layer Count:	Sample Lead Time	Volume order lead time
2L	4 days	10 days
4L	5 days	11 days
6L	6 days	12 days
8L	8 days	14 days
10L	10 days	16 days
12L	12 days	18 days
14L	14 days	20 days
16-32L	18 days	24 days

Prosessin kyky

Piirilevyjen tuotantokapasiteetit

Kerrosäärä: 1-kerros-32-kerros

Valmiiden kuparien paksuus □ 1 / 3oz-12oz

Min Rivin leveys / etäisyys sisäinen □ 3,0mil / 3,0mil

Min Rivin leveys / välinen etäisyys: 4,0mil / 4,0mil

Suurin kuvasuhde: 10: 1

Levyn paksuus □ 0,2-5,0 mm

Paneelin enimmäiskoko (tuumaa): 635 * 1500 mm

Poratun reiän vähimmäiskoko: 4mil

PI-reikätoleranssi: +/- 3mil

Blind / Buried Vias (All-tyypit): YES

Täyttämällä (johtava, johtamaton): KYLLÄ

Pohjamateriaali: FR-4, FR-4korkean painon halogeeniton materiaali, Rogers, alumiininen pohja,polyimidi,
Raskas kupari

Pintakäsittelyt: HASL, OSP, ENIG, HAL-LF, hopea,Lummersion Tina, kultaiset sormet, hiilimuste

SMT-tuotantokapasiteetit

Piirilevymateriaali: FR-4, CEM-1, CEM-3, alumiinipohjainen levy
Suurin piirilevyn koko: 510x460 mm
Minimi piirilevyn koko \square 50x50mm
Piirilevyn paksuus \square 0,5-4,5 mm
Levyn paksuus \square 0,5-4mm
Komponenttien vähimmäiskoko: 0201
Tavallinen sirukoko-komponentti: 0603 ja suurempi
Komponentin enimmäiskorkeus \square 15mm
Min. Lyijyväli: 0,3 mm
Minimi BGA-palloväli: 0,4 mm
Sijoituksen tarkkuus: +/- 0,03 mm